



SURFACE MOUNT SWITCHING DIODE

Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- High Conductance
- Miniature Package
- Lead Free/RoHS Compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability
- "Green" Device (Notes 2 and 3)

Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)

SOT-363



Top View



Top View Internal Schematic

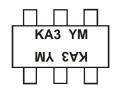
Ordering Information (Note 4)

Part Number	Case	Packaging
MMBD4448DW-7-F	SOT-363	3000/Tape & Reel

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
- 3. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



KA3 = Product Type Marking Code YM = Date Code Marking

Y = Year (ex: N = 2002)

M = Month (ex: 9 = September)

Date Code Key

Year	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	L	М	N	Р	R	S	Т	U	V	W	Х	Υ	Z	Α	В	С
Month	Jan	F	eb	Mar	Apr	М	lay	Jun	Jul	Α	ug	Sep	Oct	No	ov	Dec
Code	1		2	3	4	:	5	6	7		8	9	0	1	1	D



Maximum Ratings @ $T_A = 25$ °C unless otherwise specified

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		V_{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	75	V
RMS Reverse Voltage		V _{R(RMS)}	53	V
Forward Continuous Current (Note 5)		I _{FM}	500	mA
Average Rectified Output Current (Note 5)		lo	250	mA
Non-Repetitive Peak Forward Surge Current	@ t < 1μs @ t < 1s	I _{FSM}	4 1	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	200	mW
Thermal Resistance Junction to Ambient Air (Note 5)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-65 to +150	°C

Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition											
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	75	_	V	$I_R = 10\mu A$											
		0.62	0.720		$I_F = 5.0 \text{mA}$											
Forward Voltage	V _F		0.855	V	$I_F = 10 \text{mA}$											
1 orward voltage			1.0		$I_F = 50 \text{mA}$											
		_	1.25		I _F = 150mA											
		2.5 μA V _R = 75V		$V_R = 75V$												
Reverse Current (Note 6)	I _R	I _R	I _R		50	μA	$V_R = 75V, T_J = 150$ °C									
Reverse Current (Note 6)				IR	IR.	IR	IR IR	IR IR	IR.	IR.	'R	IR IR	I R	IR.		30
			25	nA	V _R = 20V											
Total Capacitance	C _T	_	4.0	pF	V _R = 0, f = 1.0MHz											
Reverse Recovery Time	t _{rr}		4.0	ns	$I_F = I_R = 10 \text{mA},$											
Neverse Necovery Time					$I_{rr} = 0.1 \text{ x } I_{R}, R_{L} = 100\Omega$											

Notes:

- 5. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com.
- 6. Short duration pulse test used to minimize self-heating.

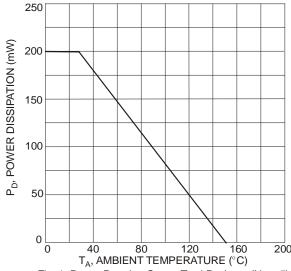


Fig. 1 Power Derating Curve, Total Package (Note 5)

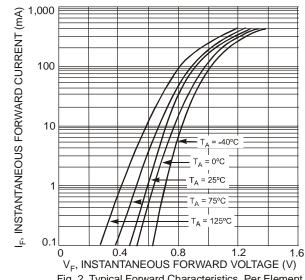
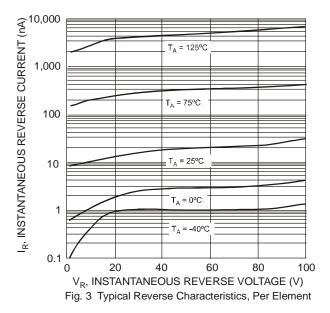


Fig. 2 Typical Forward Characteristics, Per Element





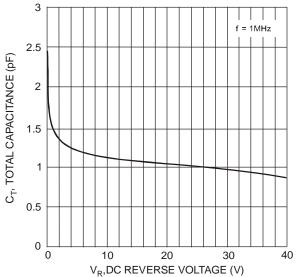
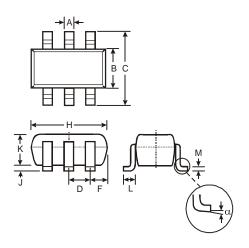


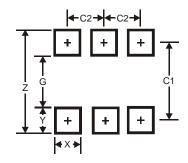
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions



SOT-363						
Dim	Min	Max				
Α	0.10	0.30				
В	1.15	1.35				
C	2.00	2.20				
D	0.65 Typ					
F	0.40	0.45				
Η	1.80	2.20				
7	0	0.10				
K	0.90	1.00				
L	0.25 0.40					
М	0.10	0.22				
α	α 0° 8°					
All Dimensions in mm						

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65



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